

# P-Channel 20-V (D-S) MOSFET

MOSFET PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)		
	0.035 at V <sub>GS</sub> = - 10 V	- 5 <sup>e</sup>			
- 20	0.043 at V <sub>GS</sub> = - 4.5 V	- 5 <sup>e</sup>	10 nC		
	0.061 at V <sub>GS</sub> = - 2.5 V	- 4.8			

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 **Definition**
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC



#### **APPLICATIONS**

- Load Switch
- PA Switch
- DC/DC Converters



ABSOLUTE MAXIMUM RATINGS $(T_A =$	= 25 °C, unless otl	nerwise noted)			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	$V_{DS}$	- 20	V		
Gate-Source Voltage		$V_{GS}$	± 12	V	
	T <sub>C</sub> = 25 °C		- 5 <sup>e</sup>		
Continuous Drain Current (T <sub>.1</sub> = 150 °C)	T <sub>C</sub> = 70 °C		- 4.8	А	
Goriana Garrena (1) = 100 G)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 4.5 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		- 3.5 <sup>b, c</sup>		
Pulsed Drain Current		I <sub>DM</sub>	- 18		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	l <sub>a</sub>	- 2.1		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 1.0 <sup>b, c</sup>		
	T <sub>C</sub> = 25 °C		2.5		
Maximum Daway Dissination	T <sub>C</sub> = 70 °C	P <sub>D</sub>	1.6	w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		1.25 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		0.8 <sup>b, c</sup>	1	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stq</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	≤ 5 s	$R_{thJA}$	75	100	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	40	50	C/ VV	

#### Notes:

- a. Based on  $T_C$  = 25 °C. b. Surface mounted on 1" x 1" FR4 board.
- d. Maximum under steady state conditions is 166 °C/W.
- e. Package limited.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static				<u>'I</u>	l		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050A		- 13.4		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μΑ		2.9		IIIV/ C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 0.5		- 1.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zana Oata Wallana B. C. C.	I <sub>DSS</sub>	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V			- 1		
Zero Gate Voltage Drain Current		$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			- 10	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 18			Α	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5.1 A		0.035			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 4.5 A	0.043			Ω	
		V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 3.7 A		0.061		1	
		V <sub>DS</sub> = - 5 V, I <sub>D</sub> = - 5.1 A		15		S	
Dynamic <sup>b</sup>	l			I	l	ı	
Input Capacitance	C <sub>iss</sub>			835			
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		180		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			155			
	V	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.1 A		10		nC	
Total Gate Charge	Qg			6.4			
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = - 10 V, V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 5.1 A		1.7			
Gate-Drain Charge	Q <sub>gd</sub>			3.4		1	
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.9	4.4	8.8	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			22	33		
Rise Time	t <sub>r</sub>	$V_{DD} = -10 \text{ V, R}_{1} = 2.4 \Omega$		20	30	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D = -4.1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		28	42		
Fall Time	t <sub>f</sub>			9	18		
<b>Drain-Source Body Diode Characteristi</b>	cs			1	L		
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 2.1		
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 20	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 4.1 A		- 0.8	- 1.2	٧	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			23	35	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	<b>-</b>		12	20	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = -4.1 \text{ A, dI/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$		15			
Reverse Recovery Rise Time	t <sub>b</sub>			8		ns	

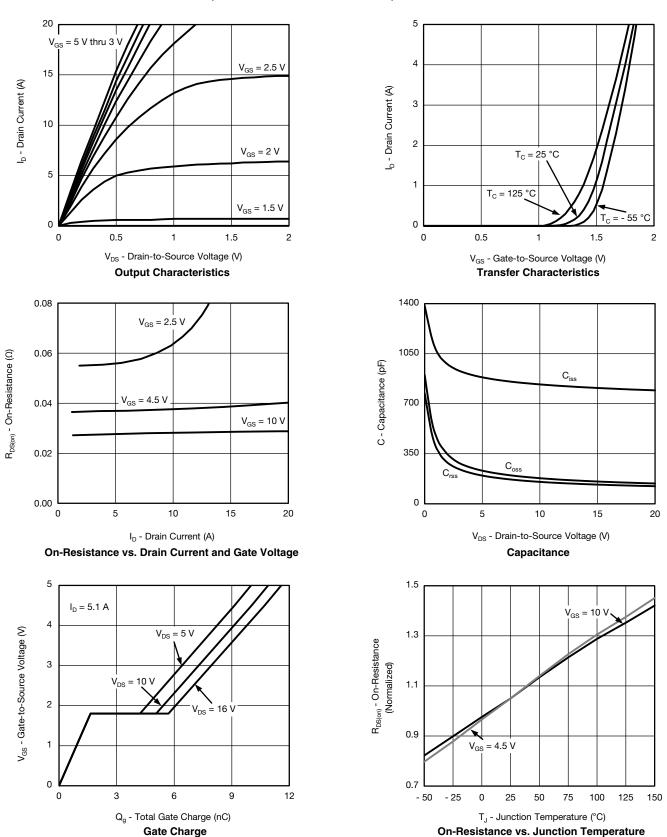
#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

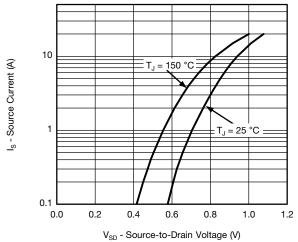
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

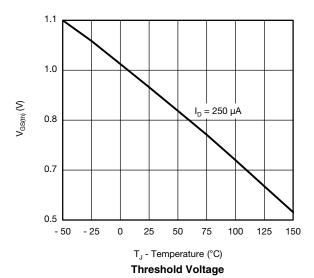






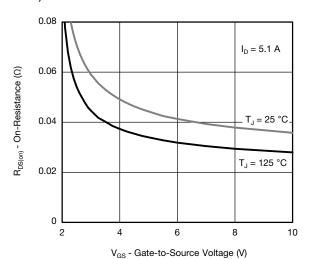


Source-Drain Diode Forward Voltage

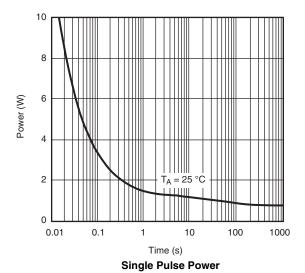


100

0.01



On-Resistance vs. Gate-to-Source Voltage



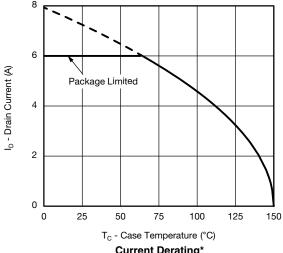
10 (V) μομη 100 μs 1 100 μs 100 ms 1 1 s, 10 s DC 1 T<sub>C</sub> = 25 °C BVDSS Limited DC

 $$V_{\rm DS}$$  - Drain-to-Source Voltage (V)  $^*$   $V_{\rm GS}$  > minimum  $V_{\rm GS}$  at which  $R_{\rm DS(on)}$  is specified

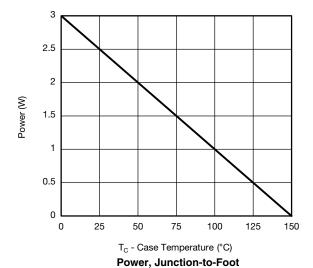
100

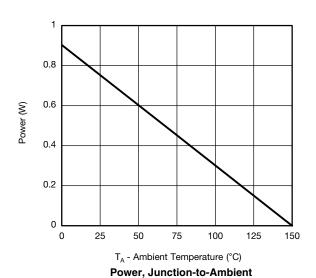
Safe Operating Area





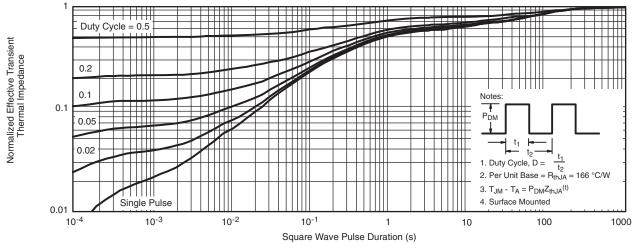




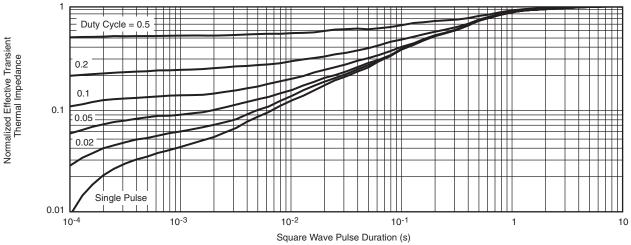


 $<sup>^*</sup>$  The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150  $^{\circ}$ C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





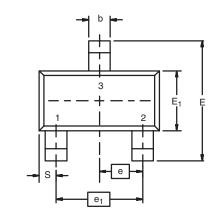
Normalized Thermal Transient Impedance, Junction-to-Ambient

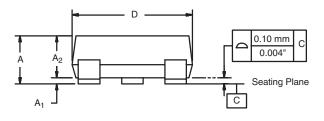


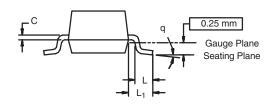
Normalized Thermal Transient Impedance, Junction-to-Foot



# SOT-23 (TO-236): 3-LEAD





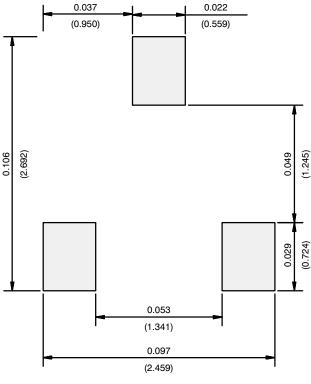


Dim	MILLIMETERS		INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e <sub>1</sub>	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	

DWG: 5479



#### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index



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